

# IRL540NL-VB Datasheet N-Channel 100-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)			
100	0.0085 at V <sub>GS</sub> = 10 V	100			
	0.010 at V <sub>GS</sub> = 6 V	85			

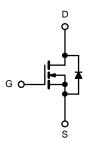
#### **FEATURES**

- Trench Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC









N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>A</sub> = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage			100	V	
Gate-Source Voltage			± 20	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	100		
	T <sub>C</sub> = 125 °C		75 <sup>a</sup>	A	
Pulsed Drain Current	I <sub>DM</sub>	300	A		
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	75		
Single Pulse Avalanche Energy <sup>b</sup>	L = 0.1 IIII1	E <sub>AS</sub>	280	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C (TO-220AB and TO-263)	P <sub>D</sub>	250 <sup>c</sup>	W	
	T <sub>A</sub> = 25 °C (TO-263) <sup>d</sup>		3.75		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) <sup>d</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Ambient	Free Air (TO-220AB)	□ □thJA	62.5		
Junction-to-Case		R <sub>thJC</sub>	0.6		

#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			•	•			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100		V		
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.0085			
D	D	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A		0.010		Ω	
Drain-Source On-State Resistance <sup>a</sup>	H <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C		0.017			
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C		0.022			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A	25			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		6550		pF	
Output Capacitance	C <sub>oss</sub>			665			
Reverse Transfer Capacitance	C <sub>rss</sub>	]		265			
Total Gate Charge <sup>c</sup>	$Q_g$			105	160		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$		17		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$	7		23			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			12	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		90	135		
Turn-Off DelayTime <sup>c</sup>	t <sub>d(off)</sub>	$I_D\cong 85~A,~V_{GEN}=10~V,~R_g=2.5~\Omega$		55	85	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	7		130	195		
Source-Drain Diode Ratings and Cha	racteristics T <sub>C</sub>	= 25 °C <sup>b</sup>	•	•			
Continuous Current	I <sub>S</sub>				85	^	
Pulsed Current	I <sub>SM</sub>				240	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 85 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			85	140	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, dI/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	$\neg$		0.17	0.35	μC	

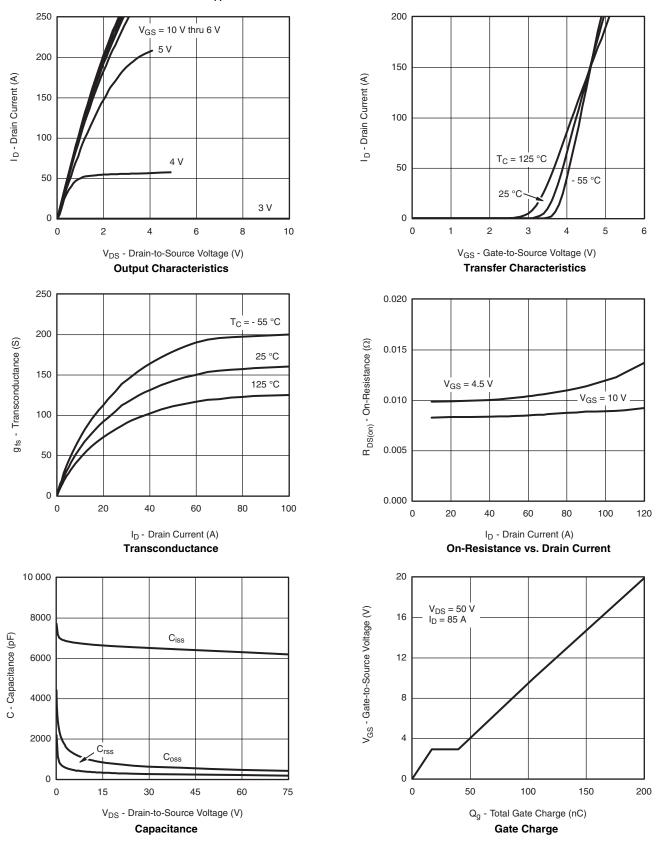
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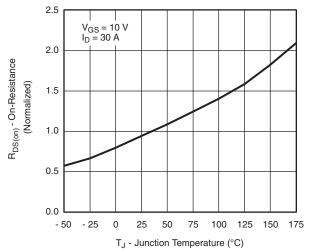
**TYPICAL CHARACTERISTICS**  $T_A = 25 \, ^{\circ}C$ , unless otherwise noted



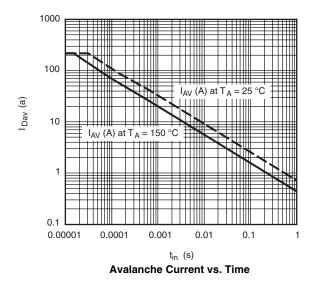
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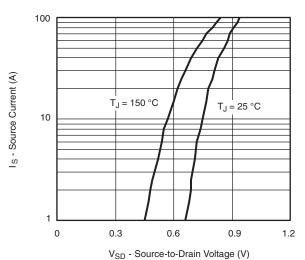


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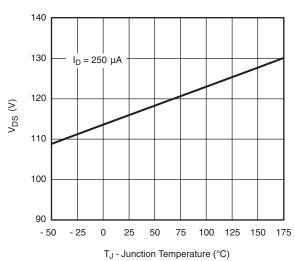


#### On-Resistance vs. Junction Temperature





Source-Drain Diode Forward Voltage



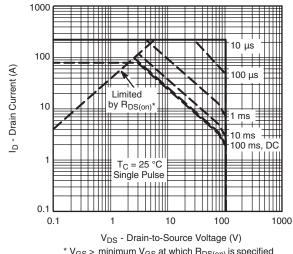
T<sub>J</sub> - Drain-Source Breakdown vs. Junction-Temperature



#### **THERMAL RATINGS**

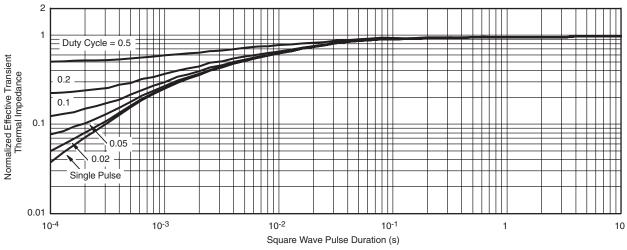






\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area



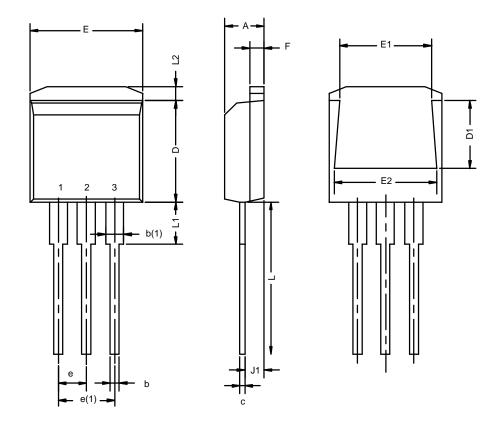
Normalized Thermal Transient Impedance, Junction-to-Case

服务热线:400-655-8788

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#### TO-262: 3-LEAD



	MILLIMETERS*		INC	HES	
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
E	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

<sup>\*</sup>Use millimeters as the primary measurement



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